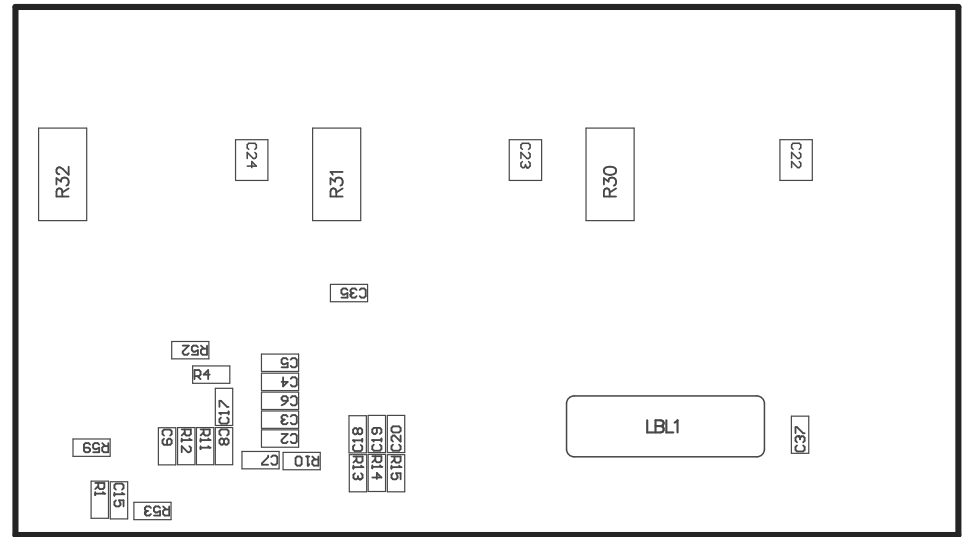


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDM-1003	REV: E1	SUN REV: Not In VersionControl
IGNORE ->			
PLOT NAME = Top Assembly Drawing	GENERATED : 2/19/2017 7:48:08 PM	TEXAS INSTRUMENTS	



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDM-1003	REV: E1	SUN REV: Not In VersionControl
	IGNORE ->		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 2/19/2017	7:48:10 PM	TEXAS INSTRUMENTS

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